	प्रतिभूति मुद्रणालय	GI FA
SEC	URITY PRINTING PRESS	The Charles
	<mark>।</mark> द्रण तथा मुद्रा निर्माण निगम लिमिटेड की इ	
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No. 6000017374/SPPH/A-II/E-413	/2022-23/2181	Date: 28.09.2022

CORRIGENDUM

This is to notify that against Tender Enquiry No. 6000017374/SPPH/A-II/E-413/2021/4880 dated 29.03.2022 for Supply, Installation, Testing and Commissioning of Fully Automated In-line Smart Card Manufacturing Machine for Contactless Cards, Qty-01 No amendment is as follows:

SI. No.	FOR	READ AS
Section-	VII: Technical Specifications – Annexure-A	
1	Technical Specifications for manufacturing and supply of 01 no. of fully automated In-line Smart Card Manufacturing machine, at Security Printing Press, Hyderabad	Technical Specifications for Manufacturing, Supplying, Instal -lation & Commissioning of 01 No. of fully automated In-line / Off-line Integrated Contactless Smart Card Manufacturing machine(s), at Security Printing Press, Hyderabad
2	Clause No. 1: A State of the art technology system fully automated In-line Smart Card Manufacturing machine having provision to control the machine through computerized console.	Clause No. 1: A State of the art technology system fully automated In- line/ Offline integrated Smart Card Manufacturing machine having provision to control the machine through computerized console.
3	Clause No. 3: Broad requirements of Fully Automatic Inline ID Card & Data-page Manufacturing	Clause No. 3: Broad requirements of Fully Automatic Inline/offline integrated ID Card & Data-page Manufacturing.
4	Clause No. 5: Throughput: up to 4,000 contactless ID1 size cards/hour; up to 1000 ID3 size PC passport data-pages (500 nos. in 2-up format)	Clause No. 5: Throughput: Minimum 4,000 contactless ID1 size cards/hour; Minimum 1000 ID3 size PC passport data-pages (500 nos. in 2-up format) at each manufacturing stage for integrated Off-line system as well as at the final stage of both In-line and Off-line integrated systems.
5	Clause No. 8: Output yield should be min. 97%; i.e. max. rejection should not exceed 3%.	Clause No. 8: Overall Output yield after final stage should be min. 97%; i.e. max. rejection after final stage should not exceed 3% for both Offline Integrated system and In-line manufacturing systems.

6	Clause No. 9: Descended requirement for	Clause No. 9: Personnel requirement for
0	Clause No. 9: Personnel requirement for operation & production line should be	Clause No. 9: Personnel requirement for the operation & production of the
	max. 6 persons. Bidders has to confirm in	complete ID card production line should
	writing.	be confirmed by the Bidder.
7	Clause No. 10: The machine should be	Clause No. 10 The machine(s) should be
	heavy-duty, sturdy and designed for 24x7	heavy-duty, sturdy and designed for 24x7
	operations.	operations.
		Clause No. 10.1. In case of Inline
		solution, RFID inlay UID nos. to be
		recorded of each chip at the point of
		feeding and at the final Card delivery
		including automatically recording the UID
		nos. of waste generated for checking /
		cross- verifying as part of track & trace system.
		Clause No. 10.2. In case of Offline
		integrated system, RFID inlay UID nos. to
		be recorded of each chip for
		checking/cross-verifying at entry & exit
		of each offline stage of production
		process until the final card delivery including automatically recording the UID
		nos. in W.I.P and UID nos. of waste
		generated at every stage of offline
		production as part of built-in Track and
		Trace system.
8	Clause No. 12: The automatic inline card	Clause No. 12: The automatic
	production system will have the	Inline/Offline integrated Holographic
	followings functions.	Security Thread Application system.
	Clause No. 12.1 : Holographic Security	Clause No. 12.1 : Holographic Security
	Thread Application system: Application of	Thread Application system: Application
	Hologram security thread by Hot stamping process on the bottom laser	of Hologram security thread by Hot stamping process on the bottom laser
	overlay layer.	overlay layer.
		Clause No. 12.1 (a) It should apply the
		hologram in precise registration.
		Clause No. 12.1(b) It should regulate the stamping speed and the temperature to
		optimize the stamping quality.
		Clause No. 12.1(c) Stamping pressure
		should be devoid of visual defects and
		flaking.
		Clause No. 12.1(d) After hologram
		application, suitable automatic cleaning
		system to be provided to clean dust or
		flakes around hologram applied area.
	Clause No. 12.2 to 12.11	Clause No. 12.2 to 12.11 : No Change
		Clause No. 12.12 In case Off-line
		integrated system, Built-in Quality
		Inspection system should be provided to

		enable good quality output, ready to feed into the next production stage. Clause No. 12.13: Throughput: Minimum
9	Clause No. 13: Automatic Inline Collation System	4,000 contactless ID1 size cards/hour. Clause No. 13: Automatic Inline/Offline Integrated Collation System
	Clause No. 13.2 (k): The RFID inlay sheet at the point of feeding should be tested and the UID nos. recorded of each chip for checking/cross-verifying at the final card delivery end as part of track & trace system. a. Basic information of the inlay sheets: - IC Chip size: based on ISO/IEC 14443 type A & B - Antenna size: Class 1 - Frequency: 13.56 MHz. - Communication range: up to 10 cm.	Clause No. 13.2 (k): 1) In case of Inline solution, the RFID inlay sheet at the point of feeding should be tested and the UID nos. recorded of each chip for checking / cross-verifying at the final card delivery end as part of track & trace system. a. Basic information of the inlay sheets: - IC Chip size: based on ISO/IEC 14443 type A & B - Antenna size: Class 1 - Frequency: 13.56 MHz. - Communication range: up to 10 cm.
		 2) In case of Offline integrated system, RFID inlay UID nos. to be tested and recorded of each chip for checking/cross-verifying at entry & exit of Offline Integrated Collation System including automatically recording the UID nos. in W.I.P and UID nos. of waste generated as part of built-in Track and Trace system. Basic information of the inlay sheets: IC Chip size: based on ISO / IEC 14443 type A & B Antenna size: Class 1 Frequency: 13.56 MHz. Communication range: up to 10 cm.
	Clause No. 13.2(q): There should be suitable flawless inline mechanism to handle and ensure perfect registration of the collated sheets.	Clause No. 13.2(q): There should be suitable flawless mechanism to handle and ensure perfect registration of the collated sheets.
		Clause No. 13.3: In case Off-line integrated system, Built-in Quality Inspection system should be provided to enable good quality output, ready to feed into the next production stage.
10	Clause No. 14: Automatic Inline Hinge Application for ID3 data-pages.	Clause No. 13.4: Throughput: Minimum 4,000 contactless ID1 size cards/hour. Clause No. 14: Automatic Inline/Offline Integrated Hinge Application for ID3 data-pages

	Clause No. 14.1 to14.5 :	Clause No. 14.1 to14.5 : No change
		Clause No. 14.6 : In case of Offline integrated system, RFID inlay UID nos. to be recorded of each chip for checking/cross-verifying at entry & exit of Offline Integrated Hinge Application including automatically recording the UID nos. in W.I.P and UID nos. of waste generated as part of built-in Track and Trace system.
		Clause No. 14.7: In case Off-line integrated system, Built-in Quality Inspection system should be provided to enable good quality output, ready to feed into the next production stage.
		Clause No. 14.8: Throughput: Minimum 1000 ID3 size PC passport data-pages (500 nos. in 2-up format).
11	Clause No. 15: Automatic Inline Integrated Hologram application system.	Clause No. 15: Automatic Inline/offline Integrated Hologram application system.
	Clause No. 15.1 to Clause No.15.9	Clause No. 15.1 to Clause No.15.9: No change
		Clause No. 15.10: In case of Offline integrated system, RFID inlay UID nos. to be recorded of each chip for checking/cross-verifying at entry & exit of Offline Integrated Hologram application system including automatically recording the UID nos. in W.I.P and UID nos. of waste generated as part of built-in Track and Trace system.
		Clause No. 15.11: In case Off-line integrated system, Built-in Quality Inspection system should be provided to enable good quality output, ready to feed into the next production stage.
		Clause No. 15.12: Throughput: Minimum 4,000 contactless ID1 size cards/hour.
12	Clause No. 16: Automatic Inline WINDOW punching & window filler system	Clause No. 16: Automatic Inline/Offline integrated WINDOW punching & window filler system.
	Clause No. 16.1 to Clause No. 16.6:	Clause No. 16.1 to Clause No. 16.6: No Change
		Clause No. 16.7: In case of Offline

		integrated system, RFID inlay UID nos. to
		be recorded of each chip for checking/cross-verifying at entry & exit
		of Offline integrated WINDOW punching & window filler system including
		& window filler system including automatically recording the UID nos. in
		W.I.P and UID nos. of waste generated
		as part of built-in Track and Trace system.
		Clause No. 16.8: In case Off-line
		integrated system, Built-in Quality Inspection system should be provided to
		enable good quality output, ready to
		feed into the next production stage.
		Clause No. 16.9: Throughput: Minimum 4,000 contactless ID1 Size cards/hour.
12	Clause No. 18: Automatic Inline	Clause No. 18: Automatic Inline/Offline
13	Lamination system	integrated Lamination system.
	Clause No. 18.1 to Clause No. 18.18:	Clause No. 18.1 to Clause No. 18.18: No
		Change
		Clause No. 18.19: In case of Offline integrated system, RFID inlay UID nos. to
		be recorded of each chip for
		checking/cross-verifying at entry & exit
		of Offline integrated Lamination system including automatically recording the
		UID nos. in W.I.P and UID nos. of waste
		generated as part of built-in Track and Trace system.
		Clause No. 18.20: In case of Off-line
		integrated system, Built -in quality
		Inspection should be provided to enable
		good quality output, ready to feed into the next production stage.
		Clause No. 18.21: Throughput: Minimum
		4,000 contactless ID1 size cards/hour
14	Clause No. 19: Automatic Inline punching system	Clause No. 19: Automatic Inline/Offline integrated Punching system
	Clause No. 19.1 to 19.16:	Clause No. 19.1 to 19.16: No Change
		Clause No. 19.17: In case of Offline
		integrated system, RFID inlay UID nos. to be recorded of each chip for
		checking/cross-verifying at entry & exit
		of Offline integrated Punching system including automatically recording the
		UID nos. in W.I.P and UID nos. of waste

	· · · · · · · · · · · · · · · · · · ·	generated as part of built-in Track and
		Trace system.
		Clause No. 19.18: In case Off-line integrated system, Built-in Quality Inspection system should be provided to enable good quality output, ready to feed into the next production stage.
		Clause No. 19.19: Throughput: Minimum 1000 ID3 size PC passport data-pages (500 nos. in 2-up format).
15	Clause No. 21.2: Safety: to secure safety, stop button and emergency stop button need to be mounted.	Clause No. 21.2: Safety: to secure safety, stop button and emergency stop button need to be mounted. In case of Offline integrated system, individual machine should have the above facility.
	Clause No. 21.4: 3nos. sets of operation manual, maintenance (mechanical & electrical manuals and spare parts manual to be supplied in English language only.	Clause No. 21.4: 3nos. Sets of operation manual, maintenance (mechanical & electrical) manuals and spare parts manual for all units/machines to be supplied in English language only.
	Clause No. 21.5: Electrical wiring diagram and back-up CF card including all software to be provided.	Clause No. 21.5: Electrical wiring diagram, Circuit diagram and back-up CF card including all software to be provided.
	Clause No. 21.7: Power Voltage at SPP, Hyderabad is 415V+/-10%, 3 Phase, 50Hz.	Clause No. 21.7: Power Voltage at SPP, Hyderabad is 415V+/-10%, 3 Phase, 50Hz+/-5%.
16	Clause No. 22.1: The complete production line should be automatic to achieve un-interrupted production; preferably no downtime for material change.	Clause No. 22.1: In case of Inline System, the complete production line should be automatic to achieve un-interrupted production; preferably no downtime for material change. In case Offline System, the complete production line should be integrated to achieve continuous production. There should be very less/no down time for material change.
		Clause No. 22.15: In case of Off-line integrated system, the bidder should provide a Track & Trace System which integrates all stages of production to maintain the data and accounting of RFID and UID chips for both smart cards and data pages of passports.
17	Clause No. 26.3: All cost towards travel/boarding and lodging shall be borne by SPP Hyderabad.	Clause No. 26.3: All cost towards travel/ boarding and lodging of SPP Officials for PDI & Training at worksite of the supplier shall be borne by SPP Hyderabad.

18	Clause No. 27: Final Acceptance Test(FAT): After successful installation and commissioning of the machine and its	Clause No. 27: Final Acceptance Test (FAT): After successful installation and commissioning of the machine and its
	auxiliary units, the FAT will be carried out for period of 1 week consisting of 8 hours per day, confirming to machine configurations rated speed, smart card/Data page Quality, output as per the	auxiliary units, the FAT will be carried out for period of 6 working days consisting of 8 hours per day, confirming to machine configurations rated speed, production quality, output as per the
	tender specifications as given below: (As per Corrigendum No.6000017374/ SPPH/ A-II/ E-413/ 2022-23/ 1118, Dt.27- 06-2022)	tender specifications as given in the following table:
19	Clause No. 28: Final Acceptance Certificate (FAC): Upon satisfactory completion of FAT, the FAC will be issued to representative of the firm.	Clause No. 28: Final Acceptance Certificate (FAC): Upon all compliance of FAT, the FAC will be issued to the firm.

Note: In the description of the machine wherever in the tender it is mentioned as Inline may be read as Inline/Offline.

All other terms & conditions remain same.

Sd/-Manager (Materials) – CPSO (for Chief General Manager)